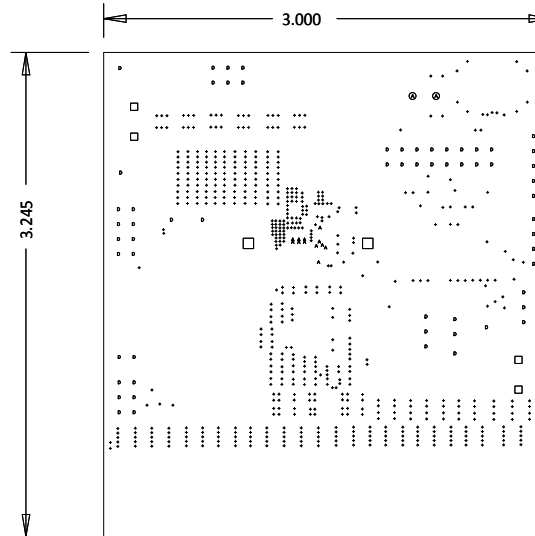


REVISIONS			
REV	DESCRIPTION	APPROVED	DATE
A	RELEASE		

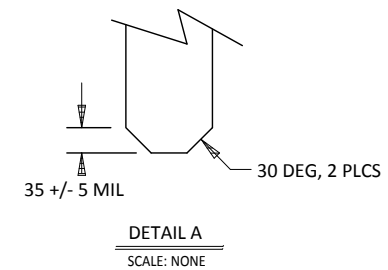
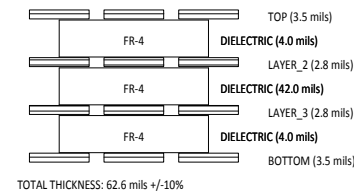
NOTES:


- 1.0 Specifications
- 1.1 Fabricate per IPC-A-600 and IPC-6012
- 1.2 Productability study - It is the responsibility of the supplier to conduct a thorough review of the artwork and media for manufacturability in the supplier's process compliance to all applicable specifications.
- 1.3 Volterra must be advised in writing (in advance of manufacturing) of any changes, revisions, or corrections made or recommendations to ensure conformance to Volterra standards, and of any specifications that cannot be met.
- 1.4 This drawing is to be used in conjunction with the provided gerber and drill data when applicable.
- 1.5 All notes are "Unless Otherwise Specified".
- 2. Material
- 2.0 Per IPC-4101A/24/26/29/98
- 2.1 Copper clad high temperature FR4 Class epoxy glass rated UL94V-0.
- 2.2 Must be RoHS compliant and survive a Lead Free assembly, maximum reflow of 260 degrees C (6 Passes)
- 2.3 T1 rating >=340 degrees C
- 2.4 Z axis CTE <3.5%
- 2.5 Tg (for reference only) choose from:
  - >150 degrees C (min), for 8 layers or less
  - >170 degrees C (min), for 8+ layers
- 3. Solder mask
- 3.0 Solder mask both sides with [GREEN color] liquid photoimageable solder mask, 003 max, thickness.
- 4. Drilling
- 4.0 All hole diameters are finished sizes.
- 4.1 All holes to be +/- .003 from true position unless otherwise specified.
- 4.2 All hole diameters to be +/- .003 unless otherwise specified.
- 4.3 An NC drill file has been supplied - see drill table.
- 5. Plating and Finishing
- 5.0 Plate the holes with copper .002" min. thickness drill size dimension apply after plating.
- 5.1 Finish coat exposed copper using OSP
- 5.2 Finished boards shall not have nicks, scratches, voids, exposed copper, poor plating, or misdrilled holes.
- 5.3 .06 mil plated trace width, .005 minimum trace width.
- 5.4 Plate fingers with .000030" gold over .000100" nickel
- 5.5 Copper thickness per "PCB CROSS SECTION"
- 6. Silkscreen
- 6.0 Silkscreen using white non-conductive epoxy or equivalent.
- 6.1 No silkscreen allowed on exposed lands or in holes which are open on solder mask layers.
- 6.2 Silkscreen must be a minimum of 3mm away from fiducial marks.
- 6.3 Minimum clearance between silkscreen legend and vias, pads, or holes to be .005.
- 6.4 Registration to be +/- .005 and must pass peel test.
- 7. Electrical Test
- 7.0 All boards shall be 100% electronically tested for opens/short at 10 volts.
- 7.1 Apply test stamp in non-legend area on solder side of PCB.
- 8. Cleanliness
- 8.0 Boards shall be free of fiberglass dust or any other foreign material.
- 8.1 Finished boards must conform to 0.01 MG/IN max NaCl ionic contamination as measured by the omega meter 600SM/DM with sufficient surrounding material to prevent shipping damage.
- 9. Packaging
- 9.0 There shall be a max of 10 units per package, individually wrapped, and shipped in cardboard cartons
- 9.1 All individual packages must be labeled with the following:
  - Maxim Part Number
  - Fab Date Code
  - QTY
  - Finish
  - RoHS Compliant
- 10. Bow and Twist
- 10.0 Bow and twist to be .007 IN/IN or .090 max according to IPC-A600D.
- 11. Inspection
- 11.0 Automatic optical inspection of all layers required.
- 12. .5mm pitch QFN component pad requirements: (If Applicable)
- 12.0 Solder mask alignment to each pad footprint area +/- .002 in respect to true position.
- 12.1 Maximum QFN devices are solder defined.
- 12.2 Solder mask pad openings shall not expose pad edge or bare FR-4.
- 13. RoHS
- 13.1 This board to be RoHS compliant.



DRILL CHART: TOP TO BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	Q
•	8.0	+2.0/-2.0	PLATED	6
▲	8.0	+3.0/-3.0	PLATED	1
▷	40.0	+3.0/-3.0	PLATED	6
□	48.0	+3.0/-3.0	PLATED	4
⊖	70.0	+3.0/-3.0	PLATED	3
⊖	47.0	+3.0/-3.0	NON-PLATED	3

4 Layer Board -- All Cu Thickness is Final  $+.0007/-0.0000$



TOLERANCES UNLESS OTHERWISE SPECIFIED:  FRACTIONS      DECIMALS      ANGLES $\pm \frac{1}{16}$ $\pm .005$ $\pm .01$ $\pm .0005$ $\pm .0005$		THE INFORMATION CONTAINED IN THIS DOCUMENT IS PROPRIETARY TO MAXIM. THE INFORMATION IN THIS DOCUMENT IS NOT TO BE SHOW, REPRODUCED, OR DISCLOSED TO ANYONE OUTSIDE OF MAXIM WITHOUT PRIOR WRITTEN PERMISSION FROM MAXIM.  DRAWN BY: WHEWLEN      DATE: 01/23/15  CHECKED BY: WHEWLEN      DATE: 01/23/15 APPR. BY: BUSZPANN      DATE: 01/23/15 APPR. BY:      DATE:		 <b>maxim</b> integrated™	
MATERIAL:		TITLE:		FABRICATION DWG. STELLA3 MOD1 EVAL BOARD	
SEE NOTES		SIZE:		DRAWING NO.:	
FINISH:		NOT TO SCALE		35-00036-01-00 TEMPLATE 89V13.1	
SEE NOTES		SHEET 1 OF 1		REV:	